

Supplier Name: Texas Instruments Inc. (DUNS# 00-732-1904)
 Contact Info: ti.com/support
 Form/Declaration Type: Distribute - RoHS and IEC 62474 DB
 Created on: 06/04/2022

Details for "OPA2387DGKT"

Current Product Information

TI part number	Lead finish/Ball material	MSL rating/peak reflow	Assembly site	Package Pins	Package body size (mm)	Total device mass (mg)*
OPA2387DGKT	SN	Level-2-260C-1 YEAR	Ext-Mfg	DGK 8	3x3x1	27.1

*Total Device Mass

The summary mass is a rounded value and will be within approximately +/- 10% of the detailed mass value.

Environmental Ratings Information

RoHS	REACH	Green	IEC 62474 DB
Yes	Yes	Yes	Yes

Component Information

Component	Substance	CAS Number	Amount (mg)	Homogeneous Material Level		Component Level	
				Percentage %	ppm	Percentage %	ppm
Bond Wire							
Not Categorized	Proprietary Materials		0.000004	0.007816	78	0.000015	0
Precious Metals	Gold	7440-57-5	0.051176	99.992184	999922	0.188645	1886
Sub-Total			0.05118	100	1000000	0.18866	1887
Die Attach Adhesive							
Precious Metals	Silver	7440-22-4	0.194918	79.999836	799998	0.718508	7185
Thermoplastics	Epoxy	85954-11-6	0.04873	20.000164	200002	0.179629	1796
Sub-Total			0.243648	100	1000000	0.898137	8981
Lead Frame							
Copper and Its Alloys	Copper	7440-50-8	11.175406	96.932995	969330	41.194859	411949
Copper and Its Alloys	Iron	7439-89-6	0.253638	2.2	22000	0.934962	9350
Copper and Its Alloys	Phosphorus	7723-14-0	0.002075	0.017998	180	0.007649	76
Other Nonferrous Metals and Alloys	Lead	7439-92-1	0.001038	0.009003	90	0.003826	38
Precious Metals	Silver	7440-22-4	0.086468	0.750004	7500	0.318739	3187
Zinc and Its Alloys	Zinc	7440-66-6	0.010376	0.089999	900	0.038248	382
Sub-Total			11.529001	100	1000000	42.498283	424983
Lead Frame Plating							
Other Nonferrous Metals and Alloys	Tin	7440-31-5	0.086	100	1000000	0.317014	3170
Sub-Total			0.086	100	1000000	0.317014	3170
Mold Compound							
Other Inorganic Materials	Fused Silica	60676-86-0	12.477358	84.999998	850000	45.994123	459941
Other Plastics and Rubber	Carbon Black	1333-86-4	0.080736	0.550001	5500	0.29761	2976
Thermoplastics	Epoxy	85954-11-6	2.121151	14.450001	144500	7.819001	78190
Sub-Total			14.679245	100	1000000	54.110734	541107
Semiconductor Device							
Ceramics / Glass	Doped Silicon	7440-21-3	0.539083	100	1000000	1.987171	19872
Sub-Total			0.539083	100	1000000	1.987171	19872
Total			27.128157			100	1000000

Important Note

The ppm calculations are at the **homogeneous material** level and are maximum concentration values. The ppm displayed represents the **homogeneous material** with the highest ppm for that substance. The amount (mg) calculations represent the maximum total amount of each substance within the component. The ppm calculations are at the **component** level and are average concentration values. The amount (mg) calculations represent the average total amount of each substance within the **component**.
[See Glossary of Terms for more details.](#)

Important Part Information

There is a remote possibility the Customer Part Number (CPN) your company uses could reference more than one TI part number. This is due to two or more users (EMSI or subcontractors) using the same CPN for different TI part numbers. If this occurs, please check your Customer Part Number and cross reference it with the TI part number seen on this page.

Product Content Methodology

[For an explanation of the methods used to determine material weights. See Product Content Methodology.](#)

Material Declaration Certificate for Semiconductor IC Packaged Products

TI certifies that the material content information provided by TI is representative and accurate to the best of their knowledge based on material information provided by its suppliers and their combination into finished IC packaged products. TI semiconductor products designated to be "Pb-free", "Green" or "RoHS Exempt" fully meets the latest EU RoHS Directive requirements along with other legislation as seen in the former JIG-101 list that has been transferred to the IEC 62474 database.

Important Information/Disclaimer

TI bases its material content information on information provided by third-party suppliers and has taken, and continues to take, reasonably diligent steps to provide any required or available information. TI may not have conducted destructive testing or chemical analysis on incoming materials and chemicals. TI and TI suppliers may consider certain information to be proprietary, and thus certain information may not be available for release by TI. The material content information is provided by TI "as is."

[For additional information, please contact TI customer support.](#)

[Signature: \(click here for a fuller statement with a signed certificate\)](#)

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 For further environmental statements, please go to www.ti.com/ecoinfo
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RoHS: Means TI semiconductor products that are compliant with the current RoHS requirement that the maximum concentration values of the ten substances listed in RoHS Annex II do not exceed 0.1 % by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI semiconductor products labeled as "RoHS Compliant" are suitable for use in specified lead-free processes. TI may also reference these types of semiconductor products as "Pb-Free." These TI semiconductor products are also fully compliant with GADSL and the IEC 62474 database for electronic requirements.

RoHS Exempt: Means TI semiconductor products that contain lead (Pb) above the RoHS Annex II threshold, but that fall within one of the specific RoHS exemptions noted above or documented in <http://www.ti.com/lit/pdf/szq088>

Green: Means the content of Chlorine (Cl) and Bromine (Br)-based flame retardants meet J5709B low halogen requirements of <=1 000ppm threshold; Antimony trioxide (Sb2O3) contained in halogen based flame retardant materials meets the <=1000ppm threshold requirement; and Beryllium Oxide (BeO) is <=1000ppm.